

6/28/03

**ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS						
<p>Application Number : 10/604,164</p> <p>Confirmation Number:</p> <p>First Named Applicant: Leonard J Gardecki</p> <p>Attorney Docket Number: BUR920030026US1</p> <p>Art Unit: 2823</p> <p>Examiner: B. KEBEDE</p> <p>Search string: ( 6354917 or 6354917 or 6354917 or 6354917 or 6354917 or 6354917 ).pn</p>							
<b>US Patent Documents</b>							
<b>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</b>							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
BH	1	6354917	2002-03- 12	Ball	B1	451	41
BH	2	6342434	2002-01- 29	Miyamoto et al	B1	438	464
BH	3	6133136	2000-10- 17	Edelstein et al		438	618
BH	4	6219910	2001-04- 24	Murali	B1	29	840
BH	5	4434434	1984-02- 28	Bhattacharya et al		357	71
BH	6	3458925	1969-08- 05	Napier et al		29	578
<b>Remarks</b>							
Note: Remarks are not for responding to an office action.							
<b>Signature</b>							
Examiner Name				Date			
Brook Kebede				11/8/2004			